# 2114 4096 Bit (1024x4) NMOS Static RAM

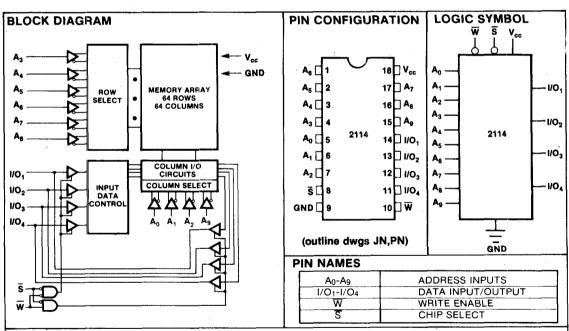
#### **FEATURES**

- · Cycle Time Equal to Access Time
- Completely Static No Clock Required
- Common Data Input and Output
- TTL Compatible Inputs and Outputs
- 883A Class B Processing Available
- Single + 5 Volt Power Supply
- Pin Compatible with industry standard 2114
- Maximum Access Time:
  - ·200 ns (-2)
  - -300 ns (-3)
- Maximum Power Dissipation:
  - 370 mW (2114L)
  - 525 mW (2114)

#### DESCRIPTION

The 2114 is a 4096-bit static Random Access Memory organized 1024 words x 4 bits. The storage cells and decode and control circuitry are completely static, therefore no clocks or refresh operations are required. Memory access occurs within the specified access time after all address inputs are stable. A Chip Select input is provided for simple memory array expansion.

The 2114 is pin and performance compatible with the industry standard 2114 series, and the device is assembled in a standard 18-pin DIP for maximum system packing density.



#### ORDERING INFORMATION

POWER				
	200ns	300ns	450ns	PACKAGE
370mW	D2114L2	D2114L3	D2114L	CERDIP
	P2114L2	P2114L3	P2114L	PLASTIC
525mW	D2114-2	D2114-3	D2114	CERDIP
	P2114-2	P2114-3	P2114	PLASTIC

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#### **ABSOLUTE MAXIMUM RATINGS**

Operating Temperature 0°C t	o +70°C
Storage Temperature65°C to	5 +150°C
Voltage on Any Pin to Ground0.5	V to +7V
Power Dissipation	1W

NOTE: Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### DC CHARACTERISTICS

TEST CONDITIONS:  $V_{CC} = +5V \pm 5\%$ ,  $T_A = 0$ °C to +70°C

			2	114L	2	114	
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	MAX	MIN	MAX	UNITS
Input Load Current	I <sub>INLD</sub>	V <sub>IN</sub> = 0V to 5.25V		10		10	
Output Leakage Current	I <sub>OLK</sub>	S = 2.4V,		10		10	μΑ
	Ì	$V_{I/O} = 0.4V \text{ to } V_{CC}$					-
Power Supply Current	I <sub>CC2</sub>	V <sub>IN</sub> = 5.25V		65		90	
		$I_{I/O} = 0 \text{mA}, T_A = + 25 ^{\circ}\text{C}$	1				
Power Supply Current	I <sub>CC1</sub>	$V_{IN} = +5.25V$		70		100	mA
		$I_{i/O} = 0$ mA, $T_A = 0$ °C	1	1			
Input Low Voltage	V <sub>IL</sub>		- 0.5	0.8	- 0.5	0.8	
Input High Voltage	V <sub>IH</sub>		2.0	V <sub>cc</sub>	2.0	V <sub>cc</sub>	V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 3.2mA		0.4		0.4	
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -1mA	2.4	v <sub>cc</sub>	2.4	V <sub>cc</sub>	

### CAPACITANCE

PARAMETER	SYMBOL	TEST CONDITIONS	MAX	UNITS	
Input/Output Capacitance	C <sub>I/O</sub>	V <sub>I/O</sub> = 0V	5	25	
Input Capacitance	Cin	V <sub>IN</sub> = 0V	5	p⊦	

NOTE: These parameters are periodically sampled, not 100% tested.

#### **DEVICE OPERATION**

When  $\overline{W}$  is high, the data input buffers are inhibited to prevent erroneous data from getting into the array. As long as  $\overline{W}$  remains high, the data stored cannot be changed by the addresses Chip Select, or data I/O voltage levels and timing transitions. The block diagram also shows data storage cannot be changed by  $\overline{W}$ , the addresses, or the input data as long as  $\overline{S}$  is high. Either  $\overline{S}$  or  $\overline{W}$  by itself, or in conjunction with the other, can prevent the extraneous writing due to signal transitions.

A read occurs during the overlap of  $\overline{S}$  low and  $\overline{W}$  high.

Data within the array can only be changed during a Write time, defined as the overlap of  $\overline{S}$  low and  $\overline{W}$  low. To prevent the loss of data, the addresses must to properly established during the entire Write time plus  $t_{wr}$ .

## **AC CHARACTERISTICS**

TEST CONDITIONS:  $V_{CC} = +5V \pm 5\%$ ,  $T_A = 0$ °C to +70°C  $t_f = t_f = 10$ ns,  $V_{IL} = 0.8V$ ,  $V_{IH} = 2.0V$ , Output Load = 1 TTL Gate and 100pF Input and Output Timing Reference Level = 1.5V

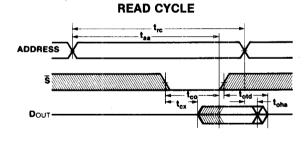
#### **READ CYCLE**

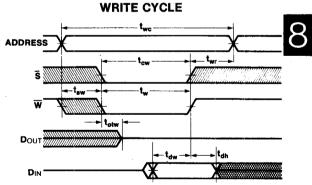
	SYMBOL	2114-2 2114L2		2114-3 2114L3		2114 21114L		
PARAMETER		MIN	MAX	MIN	MAX	MIN	MAX	UNITS
Read Cycle Time	t <sub>rc</sub>	200		300		450		
Access Time	t <sub>aa</sub>		200		300		450	
S to Output Valid	t <sub>co</sub>		70		100		100	l ns
S to Output Active	t <sub>cx</sub>	20		20		20		"
Output Three-State from Deselect	t <sub>otd</sub>	0	50	0	80	0	100	]
Output Hold from Address Change	t <sub>oha</sub>	50		50		50		]

#### WRITE CYCLE

	SYMBOL	2114-2 2114L2		2114-3 2114L3		2114 2114L		
PARAMETER		MIN	MAX	MIN	MAX	MIN	MAX	UNITS
Write Cycle Time	t <sub>wc</sub>	20Ò		300		450		
Write Time	t <sub>w</sub>	120		150		200		1
Write Release Time	t <sub>wr</sub>	0		0		0		1
Output Three-State from Write	t <sub>otw</sub>	0	60	0	80	0	100	1
Data to Write Time Overlap	t <sub>dw</sub>	120		150		200		ns
Data Hold from Write Time	t <sub>dh</sub>	0		0		0		1
Address Setup Time	taw	0		0		0		
S Select Pulse Width	t <sub>cw</sub>	120		150		200	,	

## **TIMING DIAGRAMS**





Note:  $\overline{\mathbf{W}}$  is high for a READ cycle.

## 2114 BIT MAP DIAGRAM

